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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Edward A. Schrock et al.
Title: METHOD FOR ATTACHING A SEMICONDUCTOR DIE TO A SUBSTRATE
Docket No.: 303.527US2
Filed: August 29, 2000
Examiner: John J. Gallagher
Serial No.: 09/649,827
Due Date: July 9, 2002
Group Art Unit: 1733

Box AF
Commissioner for Patents
Washington, D.C. 20231

We are transmitting herewith the following attached items (as indicated with an "X"):

- X A return postcard.
- X A Response under 37 CFR § 1.116 (9 Pages).
- X Clean Version of Pending Claims (6 Pages).
- X Clean Version of Amended Specification Paragraphs (1 pg.).

Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional required fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

By: Andrew R. Peret
Atty: Andrew R. Peret
Reg. No. 41,246

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Box AF, Commissioner for Patents, Washington, D.C. 20231, on this 10th day of June, 2002.

Name Amy Moriarty

Signature Amy Moriarty

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938, Minneapolis, MN 55402 (612-373-6900)

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EXPEDITED PROCEDURE - EXAMINING GROUP 1733

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PATENT

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RESPONSE UNDER 37 C.F.R. § 1.116

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Applicant has reviewed the final Office Action mailed April 9, 2002. Please amend the application as follows:

IN THE SPECIFICATION

Please substitute the paragraph in the appendix entitled "Clean Version of Page 10, Paragraph 2" for page 10, paragraph 2 beginning on line 9. Specific amendments to page 10, paragraph 2 beginning on line 9 are detailed in the following marked-up paragraph:

The adhesive layer(s) 46, 48 may be responsive to heat, pressure, or both. In one embodiment, the heat responsive component is a [thermoset] thermosetting material. The [thermoset] thermosetting material may be a "B-stageable" material (i.e., having an intermediate stage in which the material remains wholly or partially plastic and fusible so that it softens when heated). In yet another embodiment, the heat responsive component is a thermoplastic material.